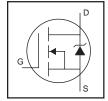
International Rectifier

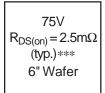
PD - 93777

IRFC2907B

HEXFET® Power MOSFET Die in Wafer Form

- 100% Tested at Probe
- Available in Tape and Reel, Chip Pack, Sawn on Film and Gel Pack**
- Ultra Low On-Resistance





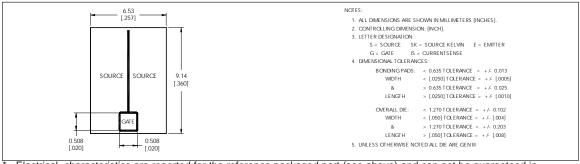
Electrical Characteristics *

Parameter	Description	Min	Тур.	Max	Test Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	75V			$V_{GS} = 0V, I_D = 250\mu A$
R _{DS(on)***}	Static Drain-to-Source On-Resistance		2.5 m Ω	4.5 m Ω	$V_{GS} = 10V, I_D = 110A$
V _{GS(th)}	Gate Threshold Voltage	2.0		4.0V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
I _{DSS}	Drain-to-Source Leakage Current			20µA	$V_{DS} = 75V, V_{GS} = 0V, T_{J} = 25^{\circ}C$
I _{GSS}	Gate-to-Source Leakage Current			± 200nA	$V_{GS} = \pm 20V$
TJ	Operating Junction and	-55°C to 175°C Max.			
T _{STG}	Storage Temperature Range				

Mechanical Data

Nominal Back Metal Composition, Thickness:	Cr-NiV-Ag (1kA°-2kA°-5kA°)		
Nominal Front Metal Composition, Thickness:	100% AI (0.008 mm)		
Dimensions:	.257" x .360" [6.53 mm x 9.14 mm]		
Wafer Diameter:	150 mm, with 100 flat		
Wafer Thickness:	0.254 mm ± 0.025 mm		
Relevant Die Mechanical Drawing Number	01-5403		
Minimum Street Width	0.107 mm		
Reject Ink Dot Size	0.51 mm Diameter Minimum		
Recommended Storage Environment:	Store in original container, in dessicated		
	nitrogen, with no contamination		
Recommended Die Attach Conditions:	For optimum electrical results, die attach		
	temperature should not exceed 300 °C		
Reference Packaged Part	IRFP2907		

Die Outline



Electrical characteristics are reported for the reference packaged part (see above) and can not be guaranteed in die sales form. Variations in customer packaging materials, dimensions and processes may affect parametric performance.

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^{**} Contact factory for these product forms.

^{***}The typical R_{DS(on)} is an estimated value for the bare die, actual results will depend on customer packaging materials and dimensions.